



Department of Electronic and Telecommunication Engineering

University of Moratuwa

Solidworks Resubmission

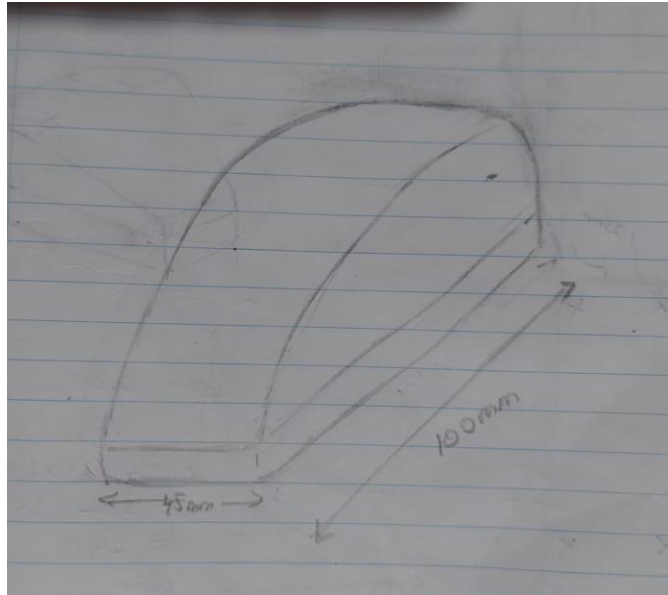
Yalegama M.M.O.A.B : 200740V

This report is submitted as a partial fulfilment of the module

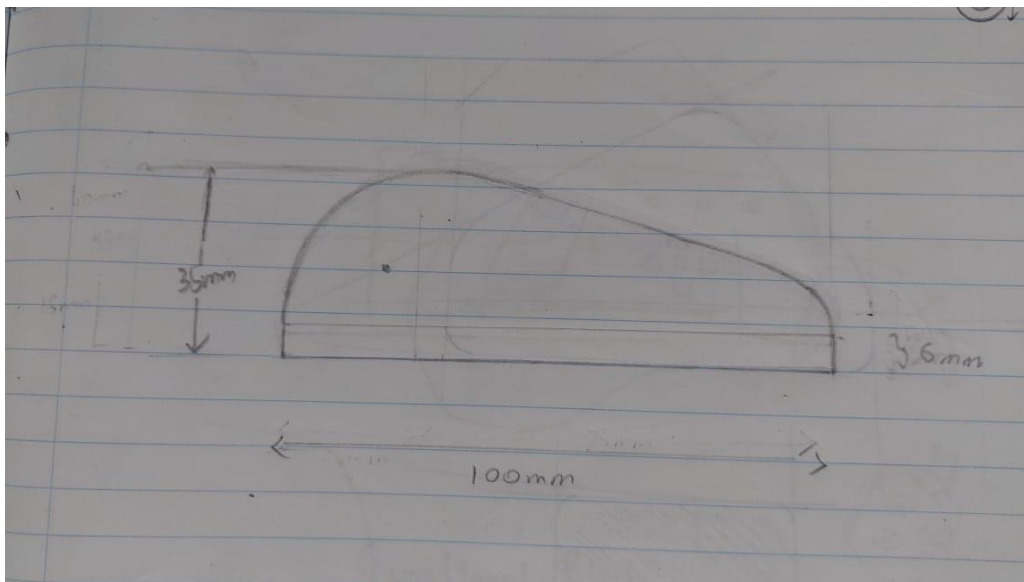
EN2160– Electronic Design Realization

08th June 2023

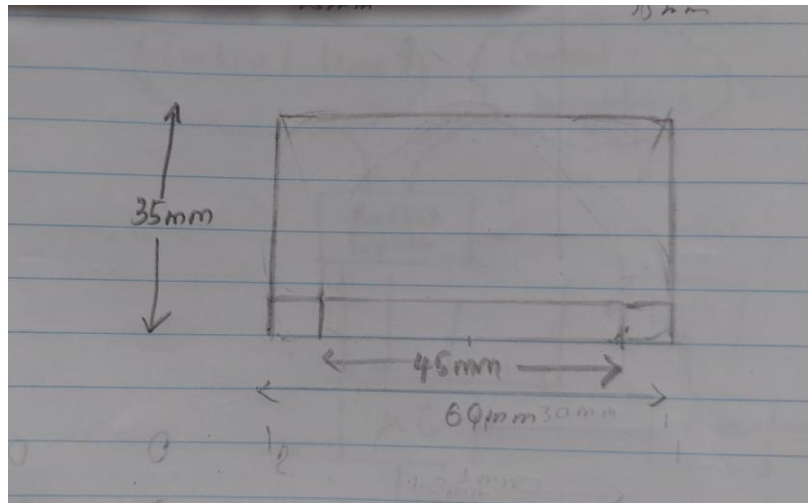
Sketches



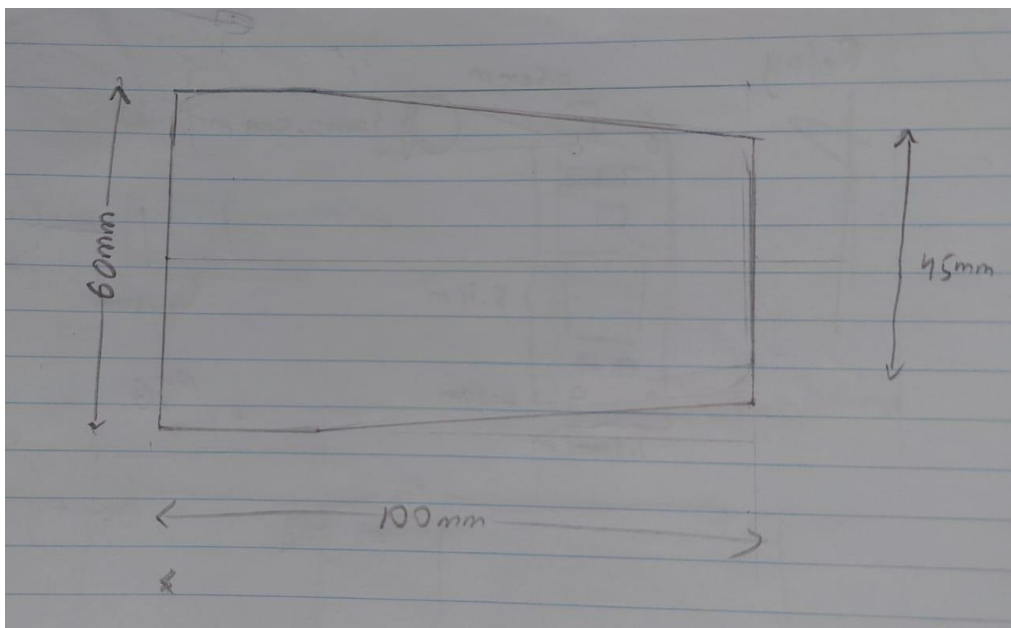
Final Enclosure



Side view

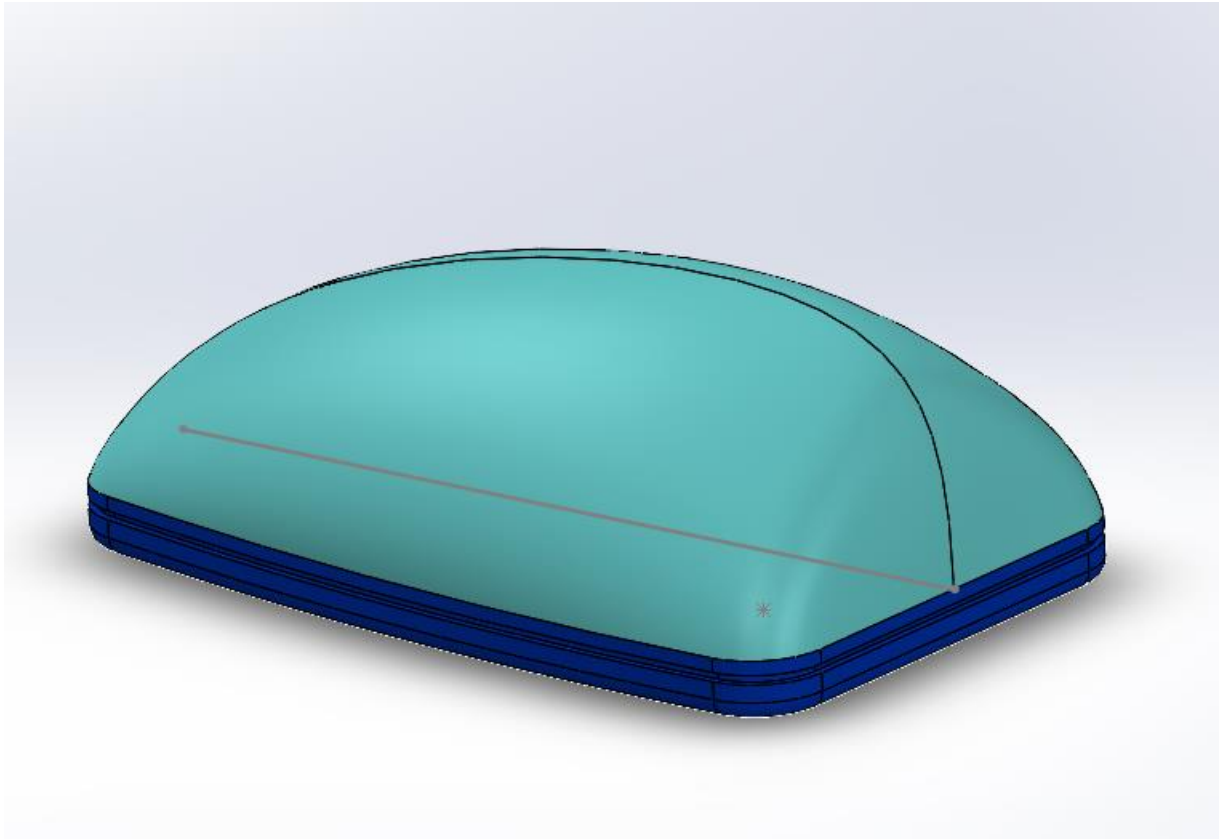


Front view

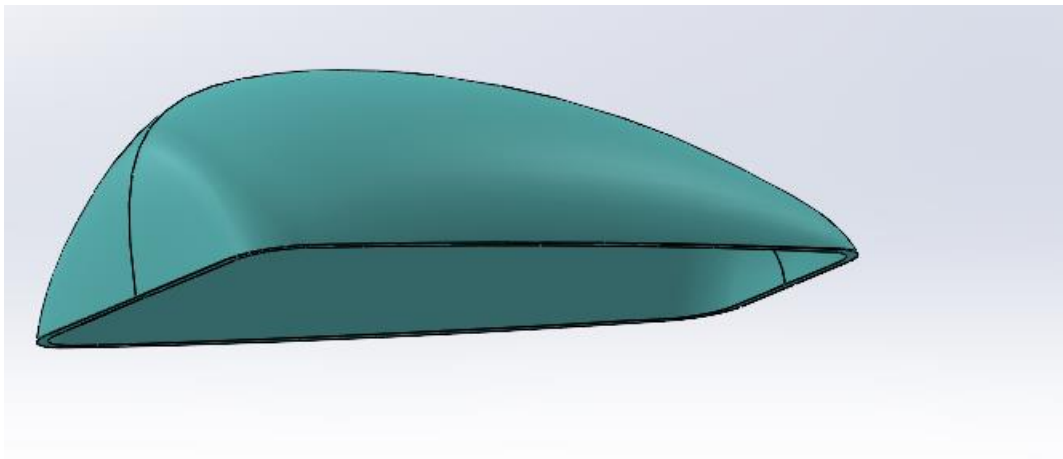


Top view

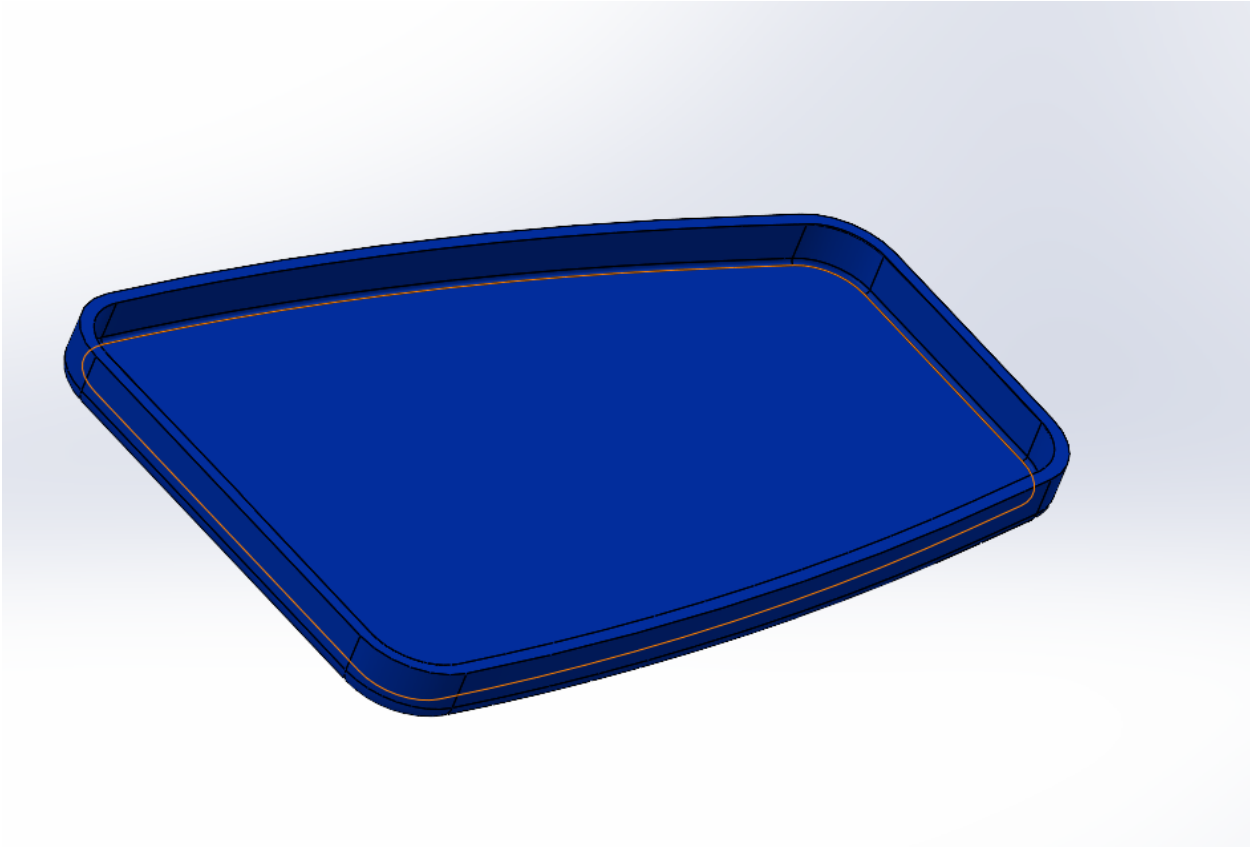
Solidworks Enclosure



Full Enclosure

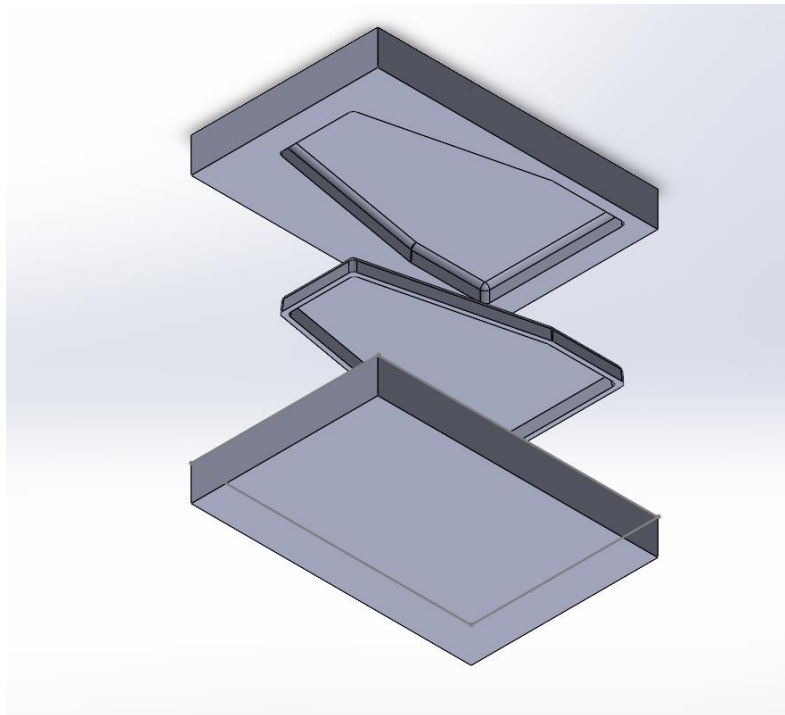


Top component

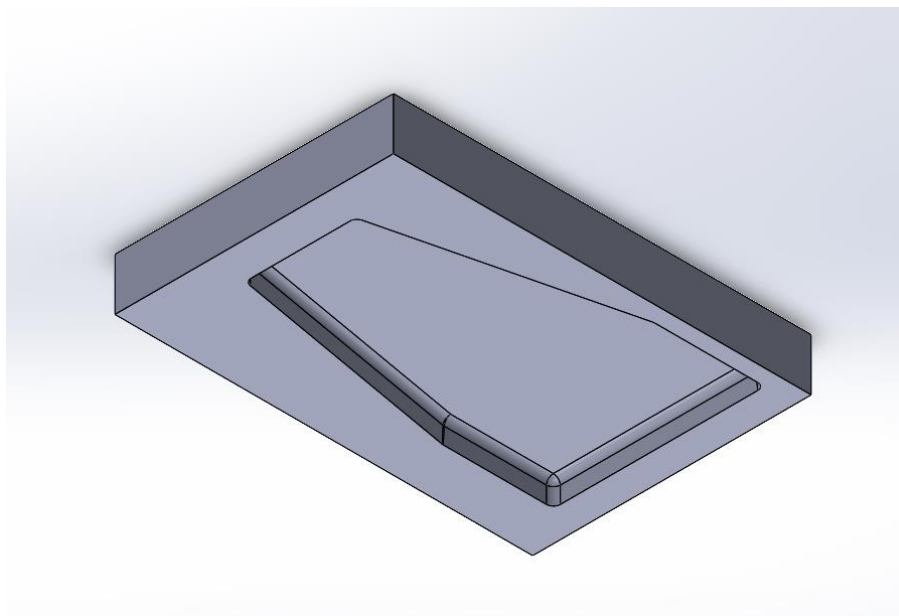


Bottom Component

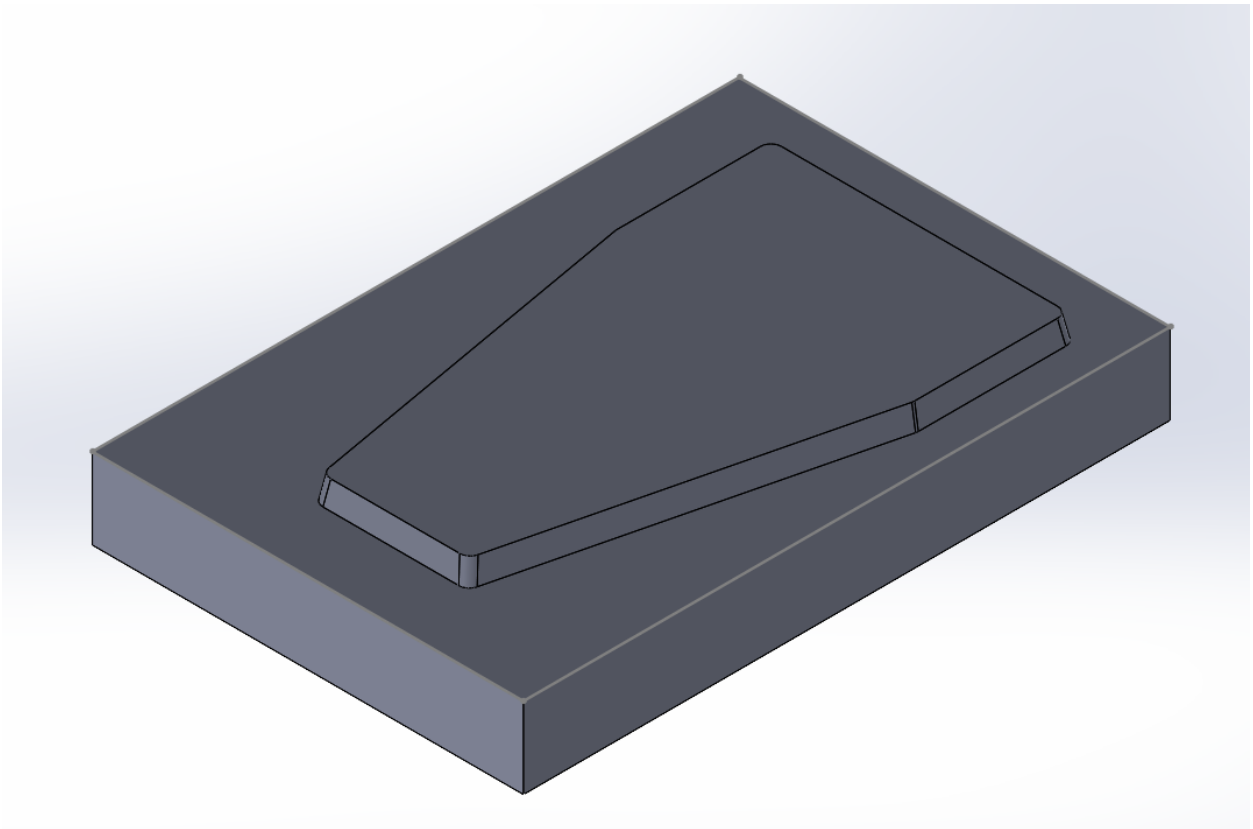
Mold Design



Core and Cavity of the bottom part of the enclosure

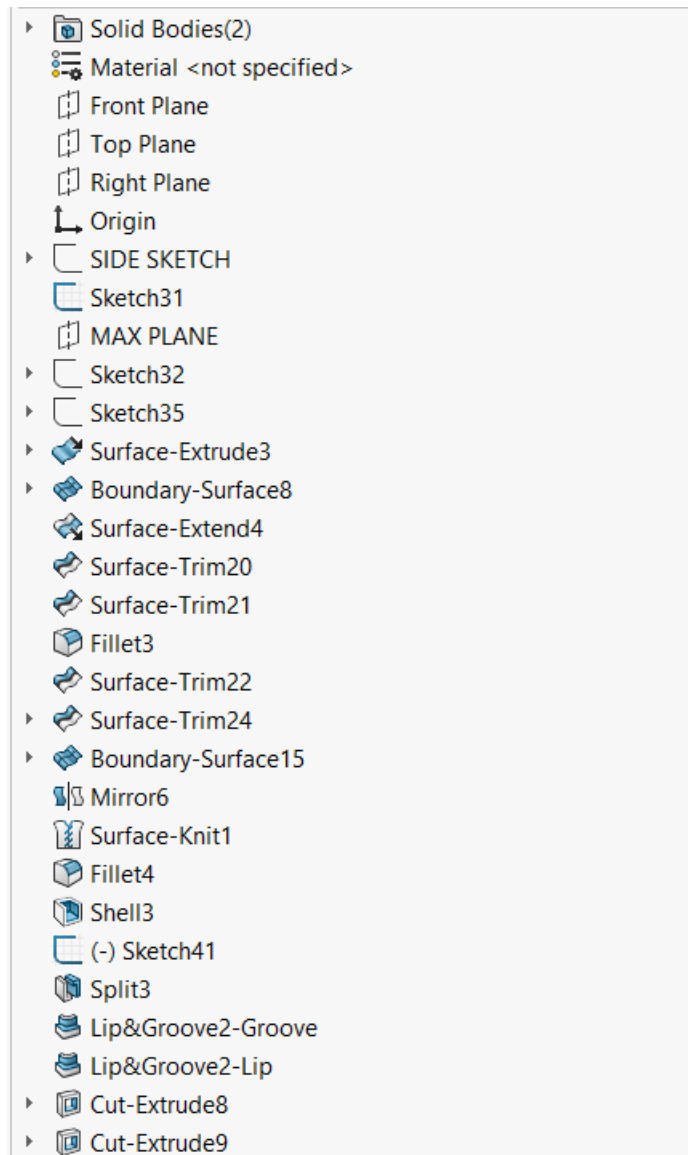


Mold Core of the bottom part of the enclosure

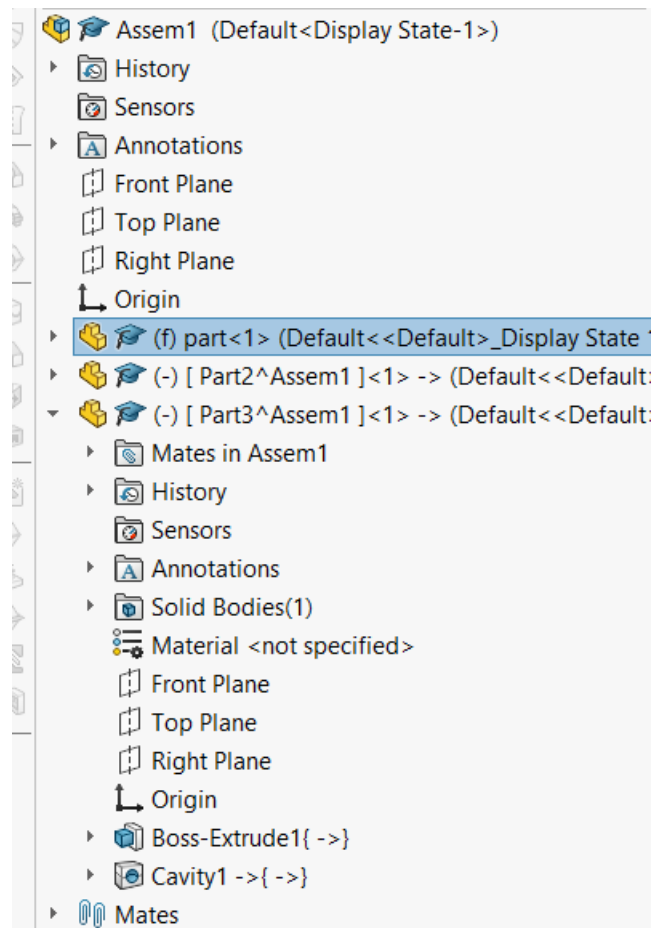


Mold Cavity of the bottom part of the enclosure

Tree Diagrams



Tree Diagram of final enclosure



Tree Diagram of mold design